

TOSHIBA IGBT Module Silicon N Channel IGBT

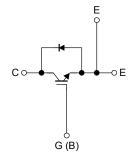
# MG400Q1US65H

High Power & High Speed Switching Applications

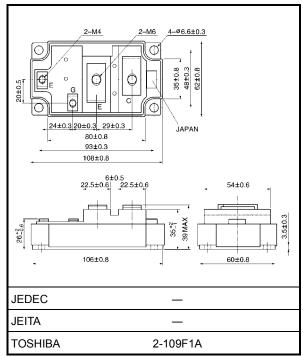
Unit: mm

- High input impedance
- Enhancement-mode
- The electrodes are isolated from case.

#### **Equivalent Circuit**



Maximum Ratings (Ta = 25°C)



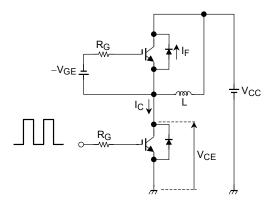
Weight: 465 g (typ.)

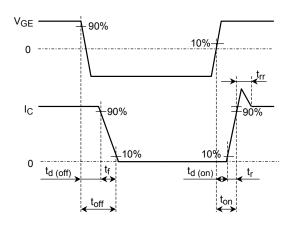
| Characteristics                            |          | Symbol            | Rating                | Unit |  |
|--|----------|-------------------|-----------------------|------|--|
| Collector-emitter voltage                  |          | V <sub>CES</sub>  | 1200                  | V    |  |
| Gate-emitter voltage                       |          | V <sub>GES</sub>  | ±20                   | V    |  |
| Collector current                          | DC       | Ι <sub>C</sub>    | 400                   | A    |  |
|  | 1 ms     | I <sub>CP</sub>   | 800                   |      |  |
| Forward current                            | DC       | ١ <sub>F</sub>    | 400                   | A    |  |
|  | 1 ms     | I <sub>FM</sub>   | 800                   |      |  |
| Collector power dissipation<br>(Tc = 25°C) |          | P <sub>C</sub>    | 2650                  | W    |  |
| Junction temperature                       |          | Тј                | 150                   | °C   |  |
| Storage temperature range                  |          | T <sub>stg</sub>  | -40 to 125            | °C   |  |
| Isolation voltage                          |          | V <sub>Isol</sub> | 2500<br>(AC 1 minute) | V    |  |
| Screw torque                               | Terminal | _                 | 3                     | N∙m  |  |
|  | Mounting | _                 | 3                     |      |  |

**Electrical Characteristics (Ta = 25°C)** 

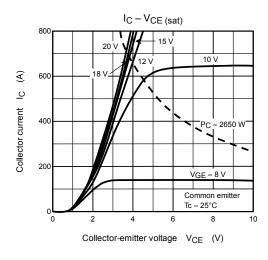
| Characteristics                      |                     | Symbol                | Test Condition   |                     | Min  | Тур.  | Max   | Unit |
|--------------------------------------|---------------------|-----------------------|--|---------------------|------|-------|-------|------|
| Gate leakage current                 |                     | I <sub>GES</sub>      | $V_{GE}=\pm 20~V,~V_{CE}=0$  |                     | _    |       | ±500  | nA   |
| Collector cut-off current            |                     | ICES                  | $V_{CE} = 1200 \text{ V}, \text{ V}_{GE} = 0$  |                     | _    | _     | 4.0   | mA   |
| Gate-emitter cut-off voltage         |                     | V <sub>GE (off)</sub> | $I_{C} = 400 \text{ mA}, V_{CE} = 5 \text{ V}$   |                     | 4.0  | _     | 7.0   | V    |
| Collector-emitter saturation voltage |                     | V <sub>CE (sat)</sub> | I <sub>C</sub> = 400 A,<br>V <sub>GE</sub> = 15 V  | $Tc = 25^{\circ}C$  | _    | 3.0   | 4.0   | v    |
|                                      |                     |                       |  | $Tc = 125^{\circ}C$ | _    | 3.6   | _     |      |
| Input capacitance                    |                     | Cies                  | $V_{CE} = 10 \text{ V}, \text{ V}_{GE} = 0, \text{ f} = 1 \text{ MHz}$   |                     |      | 34000 |       | pF   |
| Switching time                       | Turn-on delay time  | t <sub>d (on)</sub>   |  |                     | 0.05 |       | μs    |      |
|                                      | Rise time           | tr                    | Inductive load V <sub>CC</sub> = 600 V, I <sub>C</sub> = 400 A V <sub>GE</sub> = $\pm$ 15 V, R <sub>G</sub> = 2.4 $\Omega$   |                     | _    | 0.05  |       | _    |
|                                      | Turn-on time        | t <sub>on</sub>       |  |                     |      | 0.10  |       |      |
|                                      | Turn-off delay time | t <sub>d (off)</sub>  |  |                     | _    | 0.55  |       |      |
|                                      | Fall time           | t <sub>f</sub>        |  |                     |      | 0.05  |       | 0.15 |
|                                      | Turn-off time       | t <sub>off</sub>      | 1  | _                   | 0.60 | _     |       |      |
| Forward voltage                      |                     | V <sub>F</sub>        | $I_F = 400 \text{ A}, V_{GE} = 0$  |                     |      | 2.4   | 3.5   | V    |
| Reverse recovery time                |                     | t <sub>rr</sub>       | $I_F = 400 \text{ A}, V_{GE} = -10 \text{ V}$  |                     | _    | 0.25  |       | μS   |
| Thermal resistance                   |                     | R <sub>th (j-c)</sub> | Transistor stage   |                     |      | _     | 0.047 | °C/W |
|                                      |                     |                       | Diode stage  |                     |      |       | 0.1   |      |
| Switching loss                       | Turn-on             | E <sub>on</sub>       | $ \begin{array}{l} \mbox{Inductive load} \\ \mbox{V}_{CC} = 600 \ \mbox{V}, \ \mbox{I}_{C} = 400 \ \mbox{A} \\ \mbox{V}_{GE} = \pm 15 \ \mbox{V}, \ \mbox{R}_{G} = 2.4 \ \mbox{\Omega} \\ \mbox{T}_{C} = 125^{\circ}\mbox{C} \end{array} $ |                     |      | 40    |       | mJ   |
|                                      | Turn-off            | E <sub>off</sub>      |  |                     | _    | 40    | _     |      |

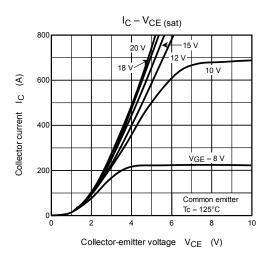
Note: Switching time measurement circuit and input/output waveforms

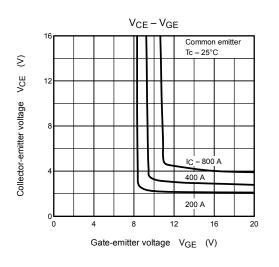


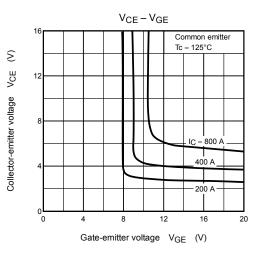


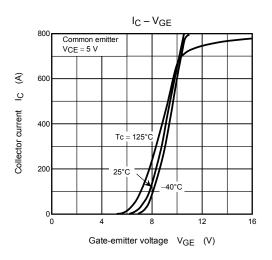
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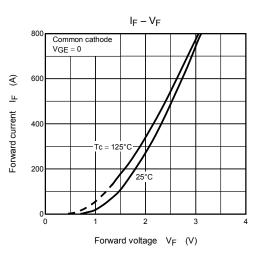


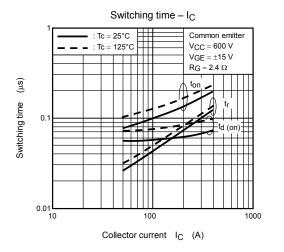


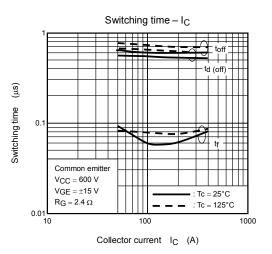




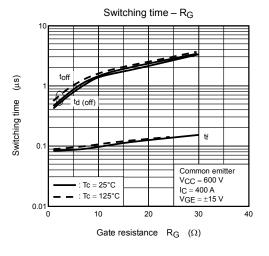


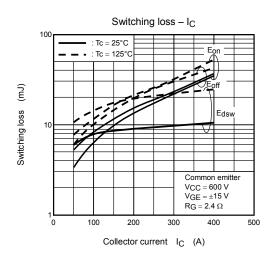


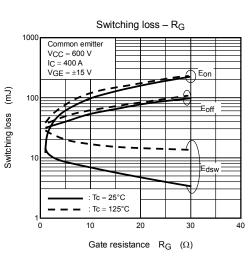




Switching time - RG on <sup>t</sup>d (on) Switching time (µs) 0.1 Common emitter VCC = 600 V IC = 400 A  $\text{Tc}=25^{\circ}\text{C}$ VGE = ±15 V :  $Tc = 125^{\circ}C$ 0.01 10 30 0 20 40 Gate resistance  $R_G$  ( $\Omega$ )

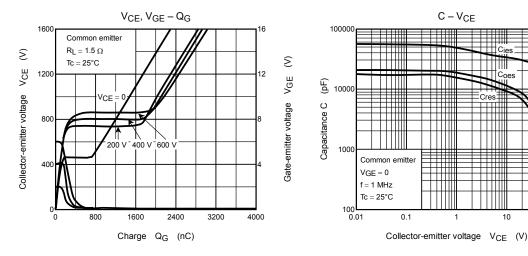


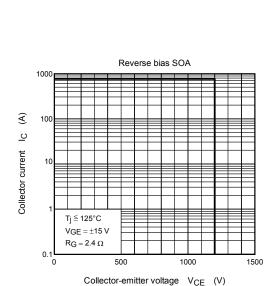


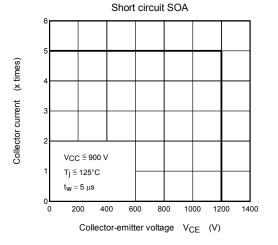


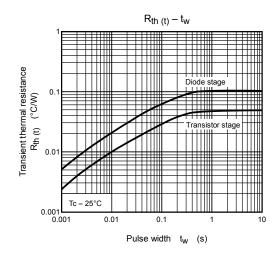
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